



## Product Change Notice

Micron PCN: 31652

Date: 08/07/2015

Revision 1, 08/14/2015: This document supersedes the original PCN #31652, dated 08/07/2015. Changes to the "Description of Change" section have been identified by red text.

**Type of Change:** Manufacturing Site – Change or Addition

**Title of Change:** Additional Fabrication and Assembly sites supporting 25nm NAND SLC Flash

**Description of Change:** Micron Fab 6 (Manassas Virginia, USA) will be added as an additional fabrication site for production of 2/4/8Gb (M79M/M70M/M71M) NAND components. Micron Muar Malaysia will be added as an additional assembly site for production of 2/4Gb VFBGA and 2/4Gb TSOP single die NAND (SDP) packages. Customers should be ready to receive product from the new sites from the production ship date below.

Product/Data Schedule:	Micron Fab 6	Micron Muar, TSOP	Micron Muar, VFBGA
Qual Data Available:	2/4Gb: May 2015	Fab 2: July 2015	Fab 2: June 2015
	8Gb: Aug 2015	Fab 6: Sept 2015	Fab 6: Sept 2015

**Reason for Change:** Additional Source/Supplier, Supply Flexibility/Security

**Contact Information:**

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**Product Affected:** 25nm NAND SLC Flash Memory

- 2/4/8Gb NAND components
- Single Die Packages VFBGA and TSOP (2/4Gb)

### Affected Micron Part Number

MT29F8G08ABACAH4:C	MT29F8G16ABBCAH4-IT:C	MT29F16G08ADBCAH4:C
MT29F8G08ABACAH4-S:C	MT29F8G08ABBCAH4:C	MT29F16G08ADBCAH4-IT:C
MT29F8G08ABACAWP-IT:C	MT29F8G08ABBCAH4-IT:C	MT29F2G08ABAFAH4-IT:F
MT29F8G08ABACAH4ES:C	MT29F8G16ABACAH4:C	MT29F2G08ABBF4H4-IT:F
MT29F4G16ABAEAH4:E	MT29F8G16ABACAH4-IT:C	MT29F2G08ABAF4WP:F
MT29F2G16ABBF4H4:F	MT29F2G16ABBF4H4-IT:F	MT29F2G16ABAF4WP:F
MT29F8G08ABACAH4-ITS:C	MT29F16G16ADACAH4:C	MT29F2G08ABBF4H4:F
MT29F8G08ABACAH4-IT:C	MT29F16G16ADACAH4-IT:C	MT29F2G08ABAF4H4-S:F
MT29F8G08ABACAWP:C	MT29F16G16ADBCAH4:C	MT29F2G08ABAF4H4-ITS:F
MT29F8G16ABACAWP:C	MT29F16G16ADBCAH4-IT:C	MT29F2G08ABAF4WP-IT:F
MT29F8G16ABACAWP-IT:C	MT29F16G08ADACAH4:C	MT29F2G08ABAF4H4:F
MT29F8G16ABBCAH4:C	MT29F16G08ADACAH4-IT:C	

**Method of Identification:** Micron's inner packing container label will indicate country of origin and fabrication site. Refer to Micron Customer Service Note CSN-11: Product Marks/Product and Packaging Labels.

**Micron Sites Affected:** Fab 6 – US  
MMY – Muar\_Malaysia

### Product/Data Schedule

#### New/Changed Product:

Sample Availability: 07/30/2015

Product Ship Date: 11/07/2015

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change